

### Gradient R&D in the US – Overview and Summary

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(on behalf of collaborators at ANL, Cornell, FNAL, JLab, and KEK)



Significant efforts have been made in recent years to improve multicell cavity gradients, driven primarily by ILC requirements (35MV/m in vertical test). Goal is to increase gradient, and gradient yield.

Here in the U.S. this effort has proceeded along several axes :

- Optimization of EP Processing
- Control of Field Emission
- Detection of Quench Origins (defects/features)
- Repair Techniques
- New Processing Methods
- Alternate Shapes

Work is ongoing, and steady progress is being made, and will be summarized here.









(5-period moving average shown)



Parameters for EP processing have been optimized and stabilized over the course of several years, based on empirical observations of cavity performance, and also through directed studies. Control of acid temperature, and lower acid temperature, has been recognized as crucial.

JLab :

- Cell temperature control (active cooling of cavity)
  - Heavy (bulk) EP : 30-35°C
  - Light EP : 25-30°C
- Constant voltage
  - Nominal 14.5V (12-17V allowable range)
- Continuous current oscillation

#### **FNAL/ANL** :

- Cell temperature control (acid temp control)
  - Bulk & Light EP : 25-30°C
- Constant voltage
  - Nominal 18V (after results at 14V gave low Q<sub>0</sub> values)
- Continuous current oscillation







Improvements in processing/cleaning techniques have helped reduce the number of cavities limited by FE and/or increase the onset of FE.

- US cleaning w/detergent after final EP
- Longer HPR (overnight)
- HOM brush cleaning
- Controlled (slow) pumpdown
- Improved/optimized tooling
- Staff consistency

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However, FE still does occur, and sometimes it occurs "spontaneously" and "permanently" degrades cavity performance.
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This "spontaneous" occurrence has been observed at least half a dozen times in the last couple of years. It often requires additional processing/remediation beyond HPR to recover performance.



All labs are now using a combination of thermometry and secondsound detectors (OST) to localize quench origins.





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Sometimes nothing (obvious) is observed.



Cavity TB9RI024, quenched at 29 MV/m.

Cavity received additional (light) EP, then reached 36MV/m.

Courtesy D. Sergatskov

Sometimes there is something obvious - but not the cause/location of the quench!

Cavity TE1AES004, quenched at 40 MV/m!

Defect is pit, ~1000 $\mu$ m (1mm!) in diameter.

Courtesy M. Ge, G. Wu





Once defects are found, especially in low-performing cavities, it would be advantageous to be able to eliminate them – i.e., "repair" the cavity – using either "global" or "local" methods.

Various techniques have been or are being developed :

Local Repair:

- Laser re-melting (FNAL)
- EB re-melting (JLab)
- Local grinding (KEK)

#### **Global Repair :**

- CBP (aka "tumbling") also considered as an alternative to traditional bulk chemical processing
- Additional light EP (not really new, of course)
- Dressed cavity EP



### Technique developed at KEK; grinder is inserted into cavity and is directed at site of defect.

Recall cavity AES003, quench limited to 20 MV/m.



### Repair Techniques – CBP/Tumbling

Like optical inspection and thermometry, all US labs now have CBP apparatus. These have been used for alternative process development and also as a "repair" tool.



Single Cell Polished to Mirror Finish





Preliminary R&D on CBP has identified a process that can yield mirror like finishes, and can eliminate the need for bulk EP.

However, so far between 40 and  $20\mu m$  of material still needs to be removed by chemistry processing (EP).

Courtesy C. Cooper

## Repair Techniques – CBP/Tumbling

Cavity TB9ACC015 tested at JLab, quench limited to 19MV/m. Thermometry identified a hot spot; optical inspection confirms defect at that location.



After EP, 200 $\mu$ m diameter feature (pit) in cell 3 near equator

Cavity received ~150 $\mu$ m CBP, light EP, 800°C/3hr HT, light EP, HPR, then 120°C/48hr bake.

After CBP and (total)  $40\mu m$  EP treatment. Pit has been removed, along with most traces of weld seam/HAZ.

Quench limit improved from 19 to 35MV/m, with Q<sub>0</sub> at quench > 1x  $10^{10}$  – meeting ILC specs!





Re-melting (via E-beam or laser) has been successfully attempted on single-cell cavities at JLab (E-Beam) and FNAL (laser).

Laser re-melting example :









Vertical electropolishing (VEP) is being studied at Cornell and JLab.

#### Potential benefits :

- eliminates rotary acid seals
- eliminates sliding electrical contacts
- eliminates some cavity handling tooling
- simplifies the acid plumbing/containment
- easier to provide cooling of external cavity surface, yielding better process control

#### **Optimizations pursued at Cornell :**

- reduce temperature of acid to 20-25°C
- reduce agitation of electrolyte
- increase voltage during EP from 14 to 17 V



Courtesy Z. Conway, M. Ge, G. Hoffstaetter

# New Processing Techniques – Vertical EP





CBP/tumbling is also being developed as a substitute for bulk EP.

#### Example : single cell cavity TE1ACC004

- bulk CBP (120μm)
- light EP (40µm)
- 800°C HT (3hrs)
- light EP (20µm)
- HPR

Courtesy C. Cooper

• 120°C bake (40hrs)

Cavity reached > 40 MV/m, with excellent  $Q_0$ , and was quench limited.





ILC-style cavities are theoretically limited to about 42-45 MV/m (for  $H_{\text{peak}}$  180-190mT).

To substantially exceed this value requires a different cavity shape (reducing  $H_{pk}/E_{acc}$ , at the expense of increasing  $E_{pk}/E_{acc}$ ).

This is being pursued at Cornell and KEK/JLab

- Cornell : Re-entrant 9-cell cavity reaches 30 MV/m after tumbling to repair defect
- KEK/JLab : Ichiro cavity #7 reaches 40 MV/m, many SC versions reach 50 MV/m

Challenges :

- high (peak) electric fields (> 100 MV/m !) lead to FE susceptibility
- cleaning and processing may be more problematic
- Q-slope, improving Q<sub>0</sub>

### Summary and Challenges





Achievement of 35 MV/m is becoming routine (meaning that we don't throw a party when we get there)... but is far from predictable or reproducible.

- Low gradient quench origins are understood observable defect, arising from welding/fabrication.
  - But have we been able to provide useful and usable feedback to vendors regarding why/how it occurs?
- High gradient quench origins, where there is no observable (surface) defect, are not well understood.
  - What is the mechanism/phenomenology responsible? How do we investigate this (surface/materials studies, cut-outs)?
    - until we understand this, we can't help vendors make better cavities, or
    - we can't (fully) understand what part of the surface process needs to be optimized/changed, and
    - we don't understand what aspect of the raw material needs to change, and
    - we don't really know what the optimum "repair" is



- Alternative processing techniques (CBP, VEP) are being developed and show promise. But have their own challenges...
  - CBP :
    - Final chemical processing still required
    - Time consuming
  - VEP :
    - Temperature control/oscillations
    - Performance levels
- Field emission is a controllable but ever-present danger.
  - can be an even greater issue as gradients push past 40 MV/m
  - development of improved techniques may be warranted
  - spontaneous FE onset and cavity degradation
- Repair techniques are being refined and becoming mature. Cavity performance improvement to ILC-levels has been demonstrated.
  - But this may not be the most economical route to achieving high yield



We have already made substantial improvements :

- high-quality raw materials
- well-controlled fabrication
- production EP optimization/control
- cleaning/rinsing/assembly optimization

Further performance improvement may require a deeper understanding of :

- quench origins that are not "visible"
- how the RF surface is affected by processing
- how RF surface parameters affect cavity performance



The progress made in achieving high gradients in nine-cell ILC cavities fabricated and processed in the US is due to the dedicated efforts of many people at the collaborating institutions and vendors : AES, ANL, Cornell, FNAL, JLab, KEK, NR, and RI. Their hard work is gratefully acknowledged.

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